IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	© Copyright 2005. IPC,	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This doct level part	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi					ials and Mfg Information				
upplier Infor	mation								,						
Company name*			Company unique ID			Unique II	Unique ID Authority					Response Date*			
nsemi							I				2023-06-08				
Contact Name			Title - Contact			Phone - C	Phone - Contact*				Email - Contact*				
Product-Env-Stev	wards		Product Enviro Compliance			NA	NA				Product-Env-Stewards@onsemi.com				
uthorized Repre	sentative*		Title - Representative			Phone - F	Phone - Representative*				Email - Representative*				
Product-Env-Stev	wards		Product Enviro Compliance			NA	NA				Product-Env-Stewards@onsemi.com				
Reques	Requester Item Number		Mfr Item Number Mfr Item Name			Effective	Date	Version Manufacturing Site		,	Weight*	UOM	Unit Type		
		NCV70514MW003AR BIPOLAR S		BIPOLAR STEPP	STEPPER MOTOR GRESHAM		2023-06-08		В	BE4		14.8	mg	Each	
lanufacturin _?	g Proccess Informatio	n													
Terminal Plating / Grid Array Material T			Perminal Base Alloy J-STD-020 MSL Rating		STD-020 MSL Rating	Peak Process Body Temperature Max Time at Pea			Max Time at Peak	k Temperature Number of Reflow Cycles					
Matte Tin (Sn) - annealed		CU	CU Alloy 3			260	260 C			30	secon	ds 3			
omments															
TTENTION: MS	SL 3 Rated item requires B	ake and Dr	y Pack (after	electrical test)							_				
or more informa	tion regarding material cor	nposition n	lease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier shall apply the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

omogeneous Material Weight		Unit of Measure	Level Substance		CAS Exempt		Weight	Unit of Measure
Die	0.25	mg	Supplier	Silicon (Si)	7440-21-3		0.25	mg
Die Attach Epoxy	0.37	mg		Epoxy resin	proprietary data		0.111	mg
			Supplier	Diethylene glycol monoethyl ether acetate	112-15-2		0.1295	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.1295	mg
Lead Frame	5.81	mg	Supplier	Silver (Ag)	7440-22-4		0.9877	mg
			Supplier	Iron (Fe)	7439-89-6		0.0465	mg
			Supplier	Copper (Cu)	7440-50-8		4.7758	mg
Mold Compound-Black	7.0	mg		Epoxy Phenol Resin	proprietary data		0.735	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.265	mg
Plating	0.41	mg	Supplier	Tin (Sn)	7440-31-5		0.41	mg
Wire Bond - Au	0.96	mg	Supplier	Gold (Au)	7440-57-5		0.96	mg